

ABSTRACT

A jig for holding and conveyance having a weak-adherence adhesive pattern on a plate surface on which a printed circuit board having a conductive portion and a non-conductive portion on the surface of an insulating substrate is placed and held. The weak-adherence adhesive pattern is formed by being restricted to a position corresponding to non-conductive portion. A jig for holding and conveyance is also disclosed which has a fluorine-based resin layer on a plate surface on which a printed circuit board having a conductive pattern on the surface of an insulating substrate is placed and held. On the fluorine-based resin layer, the printed circuit board is held so that the conductor pattern surface of the printed circuit board is approximately parallel to the plate surface. A jig for holding and conveyance can be provided which is capable of reducing manufacturing defects in a step of connecting electronic components or the like on the surface of a thin printed circuit board or in a step of manufacturing the printed circuit board, and which is capable of low-cost production.